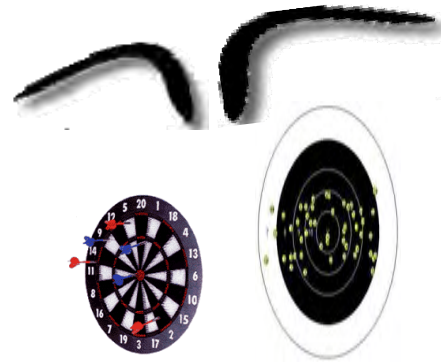




UNIwersytet WARSZAWSKI



Targets for nuclear physics studies



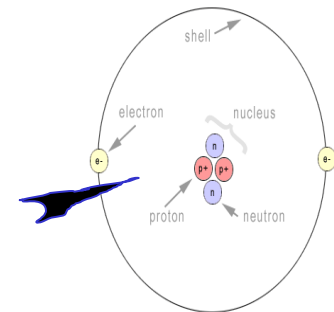
Anna Stolarz

**Heavy Ion
Laboratory**

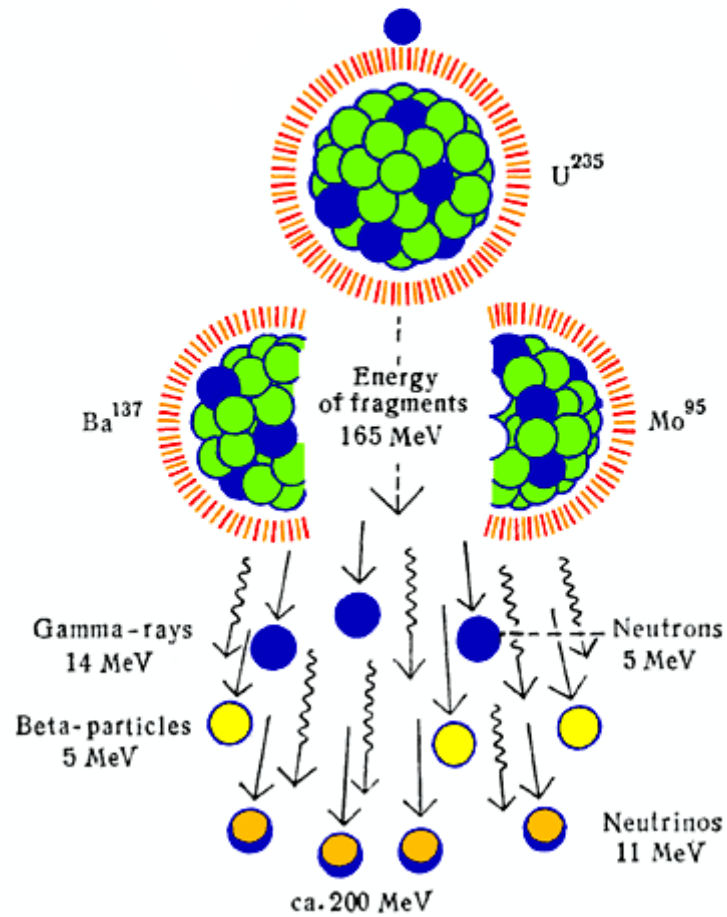
What is the target?



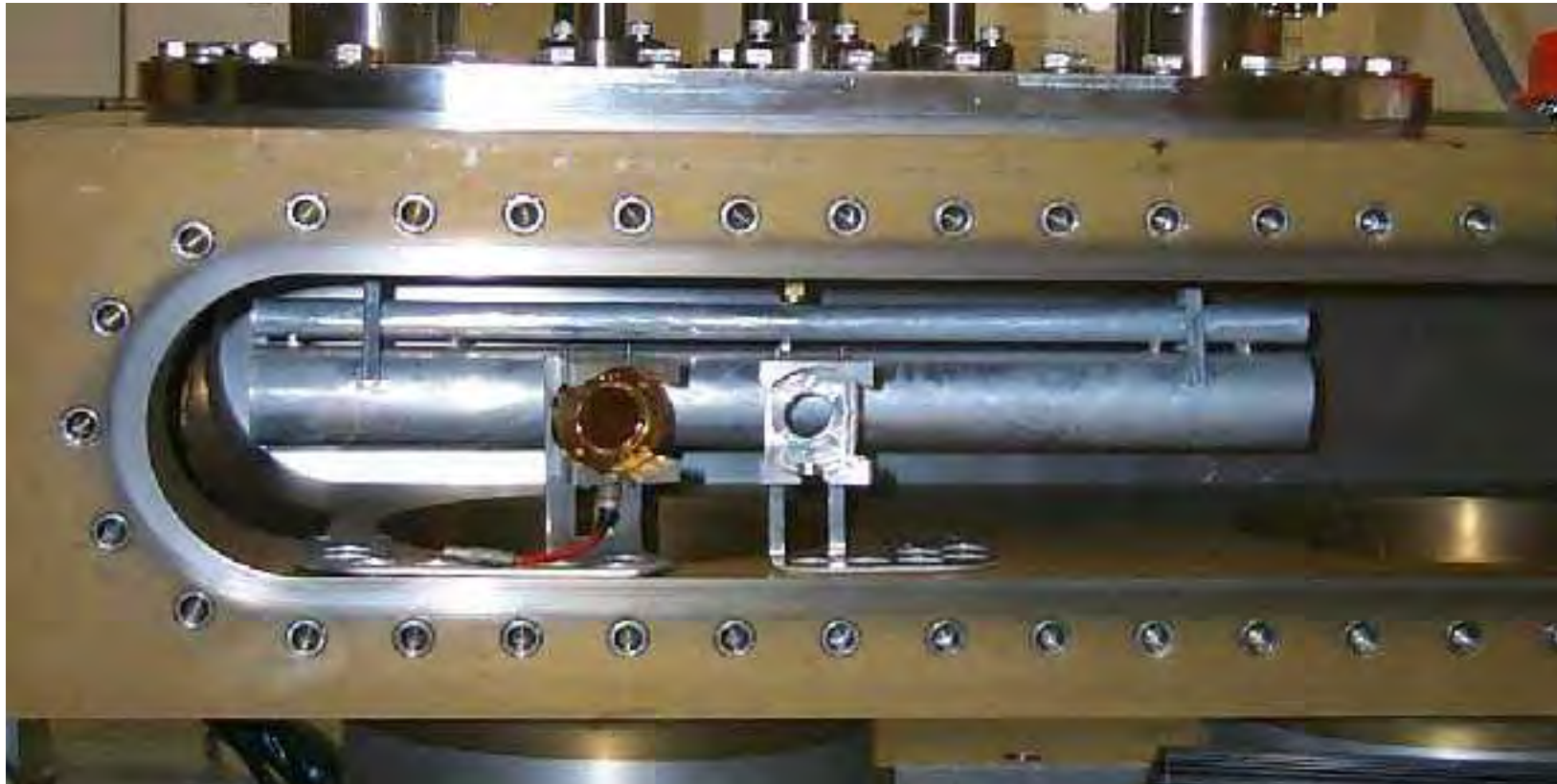
What is the target?



What is the target?



What is the target?



How to make the target?

The choice of the method depends on many aspects:

target characteristics/parameters

costs of the materials

availability of the tools/method in the target lab

effectiveness

avoiding contamination of the material (as far as possible)

How to make the target?

Target properties

Target material: element-isotope and its state:
solid, liquid, gaseous

Thickness

Chemical form required and available

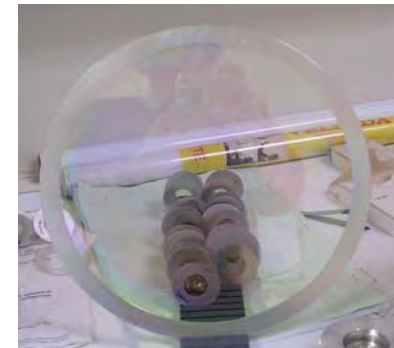
Self-supporting or on the backing

popular backings:

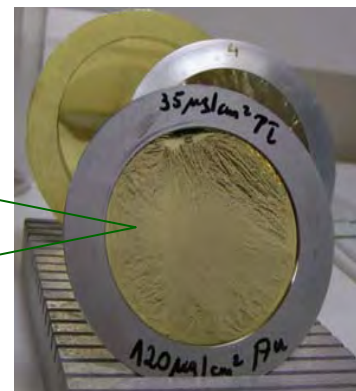
thin metal foils

carbon foil

plastic: Mylar, Kapton, Formvar



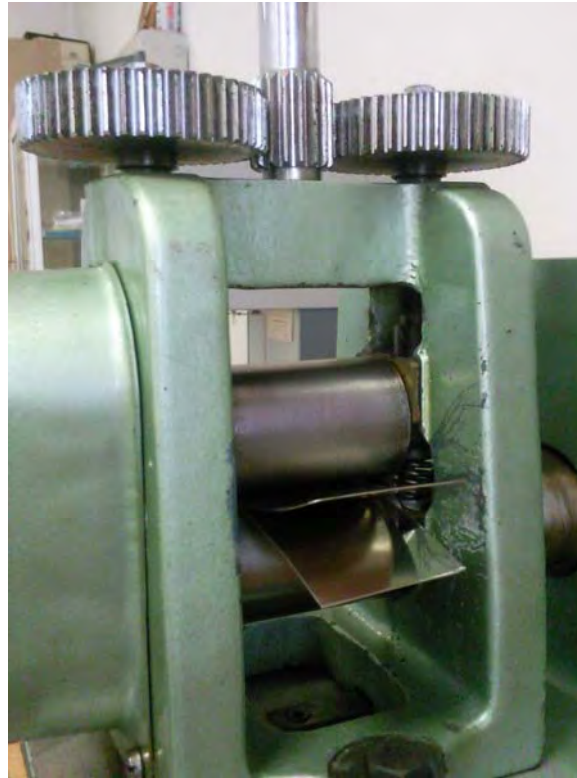
120 $\mu\text{g}/\text{cm}^2$ Au on 35 $\mu\text{g}/\text{cm}^2$ polyimide foil



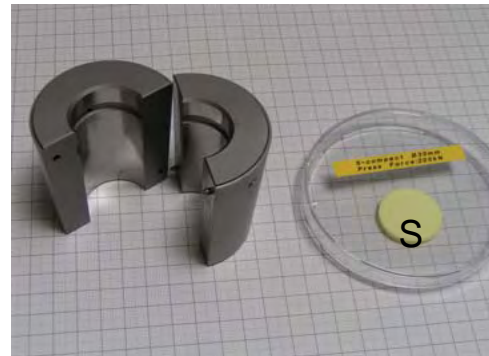
How ???

mechanical shaping:

rolling



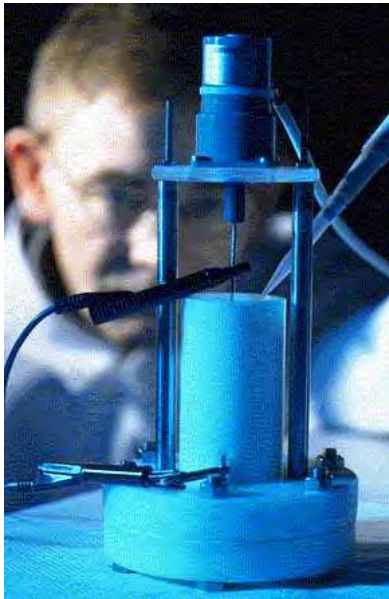
tablet pressing



How ???

chemically: electro-deposition from hydrous or organic medium

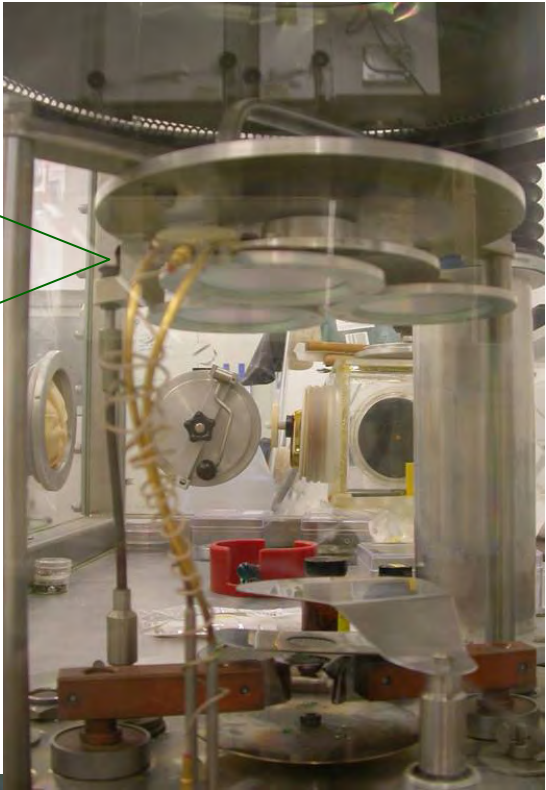
(always on the backing)



How ???

deposition in the high vacuum

Substrates rotation (to improve the thickness homogeneity of the deposited layer)



resistance heating

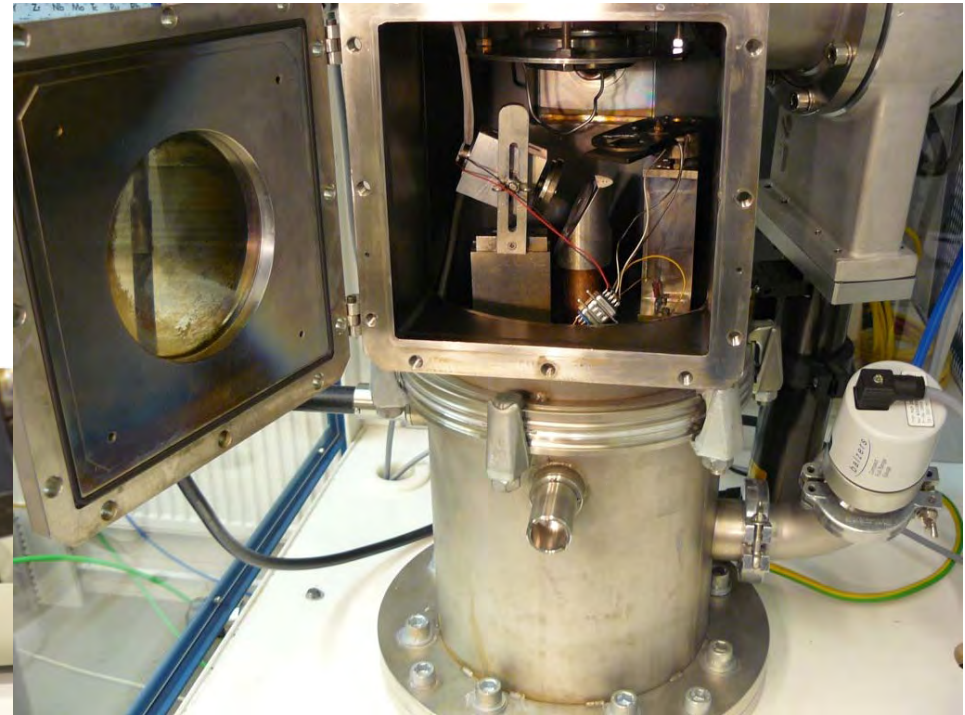


e-gun

How ???

deposition in the high vacuum

sputtering



How??

carbon evaporation:
arc
e-gun
laser ablation



How??

Resistance heating

- The method is very simple, robust but limited to the materials of the low melting point (not higher than 1500 °C) and not alloying with the boat material (typical boat material is Mo, Ta, W).

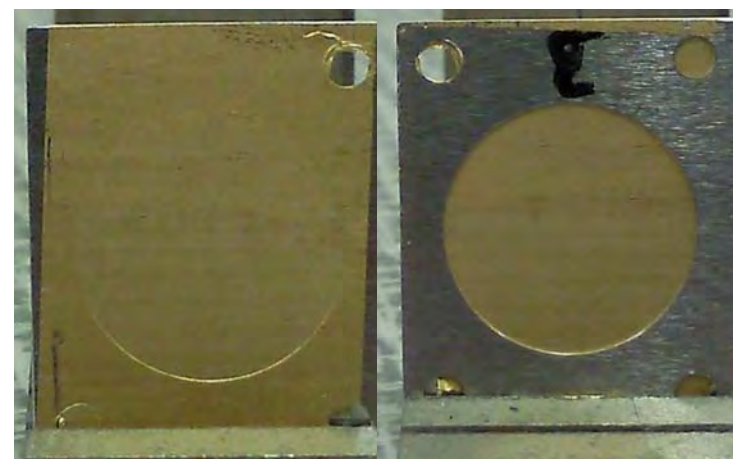
E-gun

- The method is more complex, but extremely versatile.
Can achieve temperatures in excess of 3000°C.
 - Use evaporation cones or crucibles in a water cooled copper hearth.
 - Typical emission voltage is 8-10 kV.
- but
- exposes substrates to secondary electron radiation.
 - X-rays can also be generated by high voltage electron beam

Sputtering

- the method can be applied to the most of the materials except those which can degrade due to ionic bombardment
 - this technology allows to release the deposited material at much lower temperature than evaporation.
 - gives easy film thickness control via time, allows alloy deposition, no x-ray damage
- but
- requires rather big surface of the sputtered material to avoid bombarding of the cathode material. There is as well big chance for the impurities incorporated due to low vacuum.

How ???



Target characterisation

Thickness:

(mass/area i.e. g-mg- μ g/cm²)

?

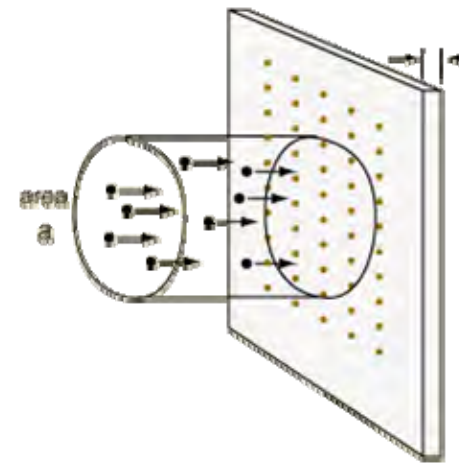
$$1 \text{ b } (\sigma) = 10^{-24} \text{ cm}^2$$

it's approx. the sectional area of
the U nucleus

The unit was created during II WW

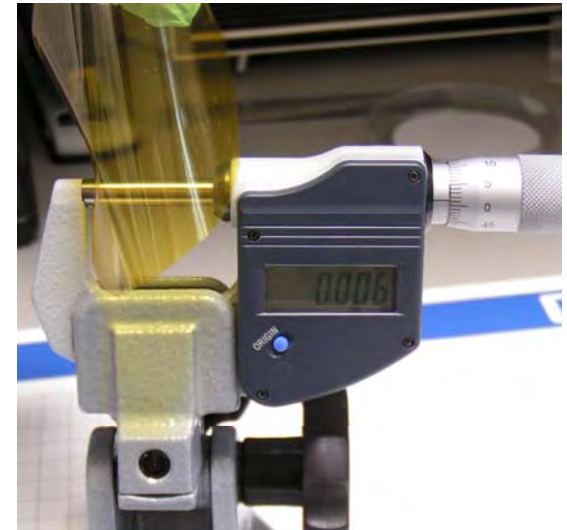
Physicists working on Manhattan project to keep
their discussions on problems related to the
atomic bomb production in secret were meeting
in the barn.

As legend wants discussing the probability of
hitting the U nucleus by neutron one said 'it
should be no problem as U nucleus comparing
to the neutron is like the barn in which we are'



Thickness estimation: mass/area i.e. g-mg- μ g/cm²)

- * mechanically i.e. caliper, micrometer (screw??)
- * weighing the defined area
- * in-situ during the vapour deposition process using the quartz microbalance
- * spectrophotometrically
- * measurement of the α particles or X-ray energy loss
- * profilometers working in a contact or non-contact modes

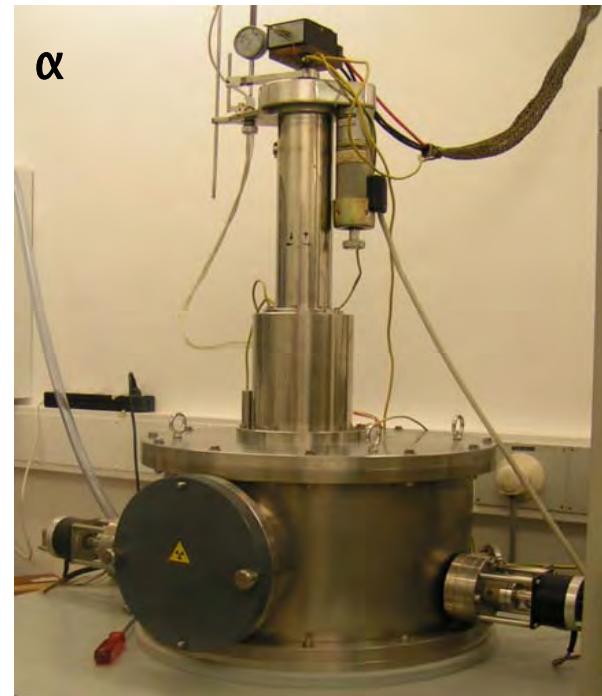


Thickness estimation of the active targets:

if made by evaporation: during preparation with quartz microbalance

ready target: measurements of the activity

thickness homogeneity by activity scan across the target area



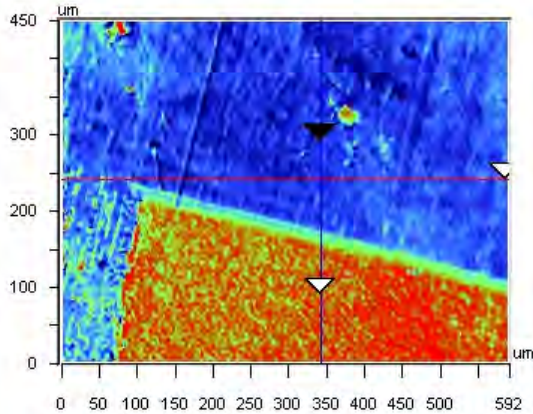
Target characterisation

Thickness: (mass/area i.e. g-mg- $\mu\text{g}/\text{cm}^2$)

Thickness homogeneity:

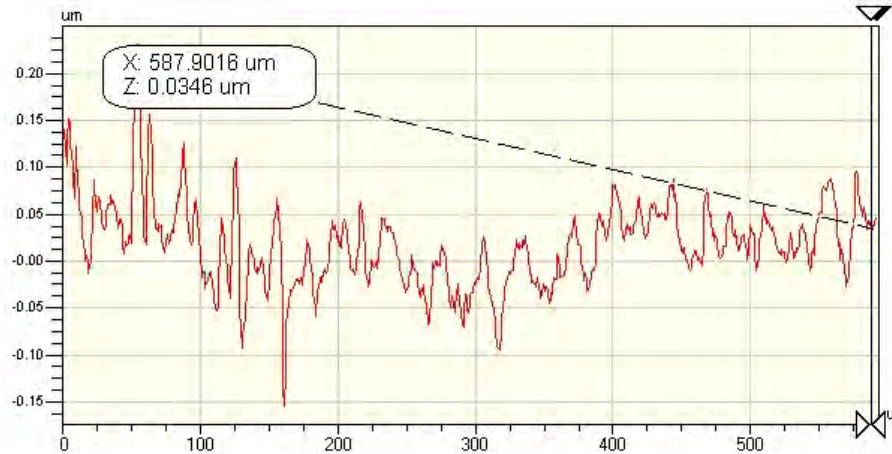
?

Surface characterisation



X	342.28	-	-	um
Y	240.53	-	-	um
Ht	-0.02	-	-	um
Dist		-	-	um
Angle		-	-	°

X Profile



Rq	0.05 um
Ra	0.03 um
Rt	0.39 um
Rp	0.23 um
Rv	-0.16 um

Angle	0.00 mrad
Curve	0.56 m
Terms	None
Avg Ht	0.02 um
Area	10.22 um ²

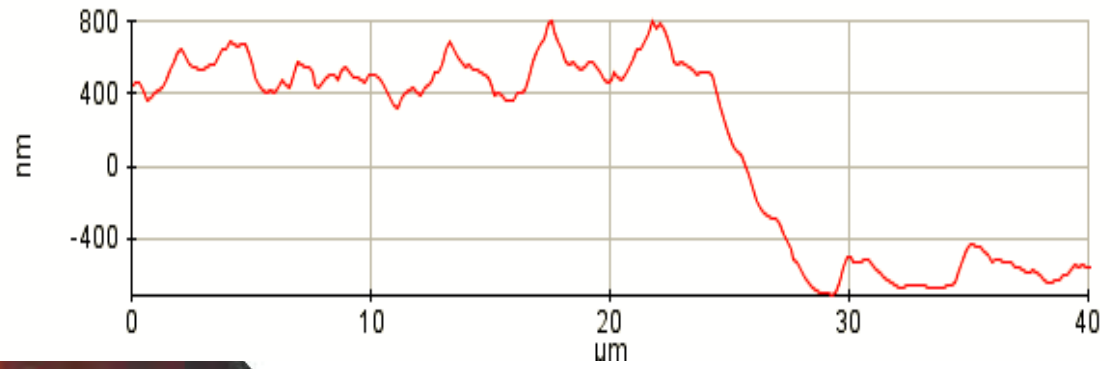
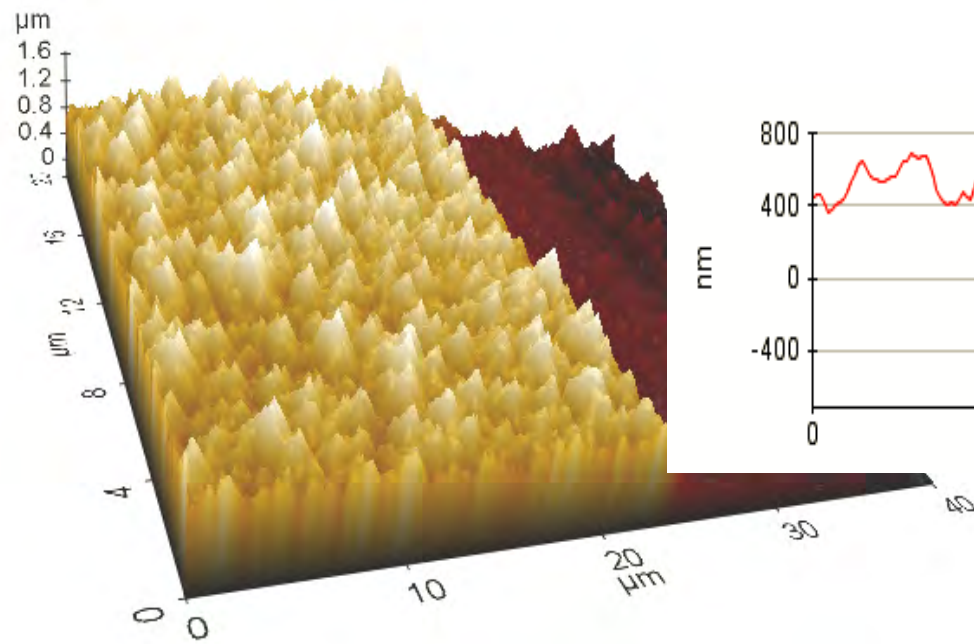
Y Profile



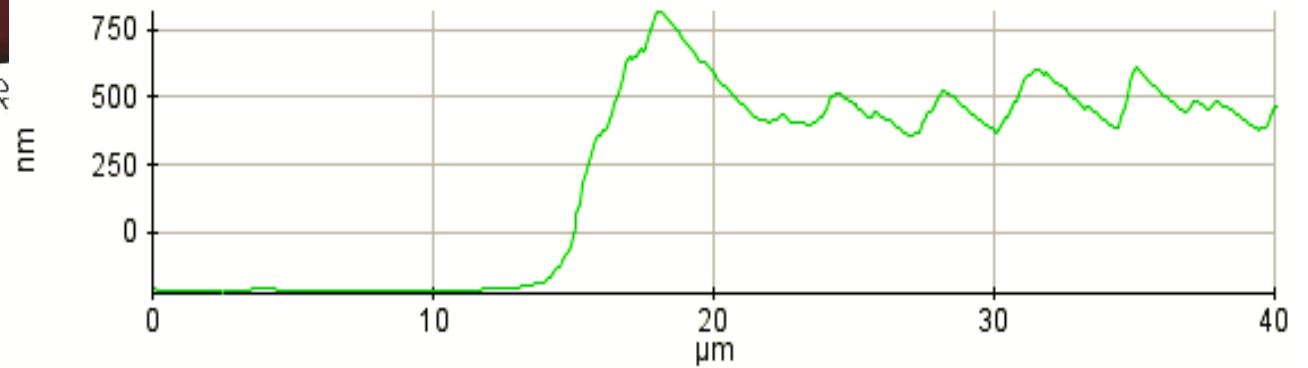
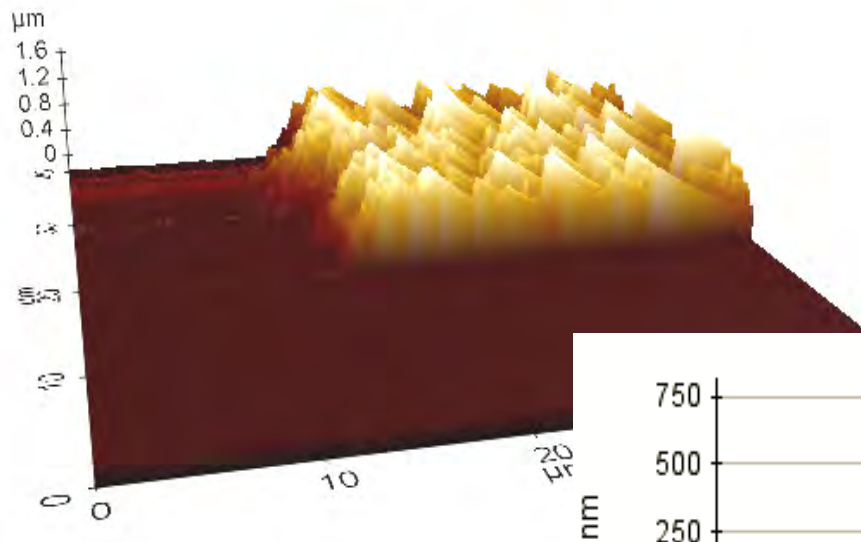
Rq	0.21 um
Ra	0.19 um
Rt	0.65 um
Rp	0.58 um
Rv	-0.07 um

Angle	-2.31 mrad
Curve	22.77 mm
Terms	None
Avg Ht	0.16 um
Area	32.59 um ²

Title:



AFM images of tristearin layer



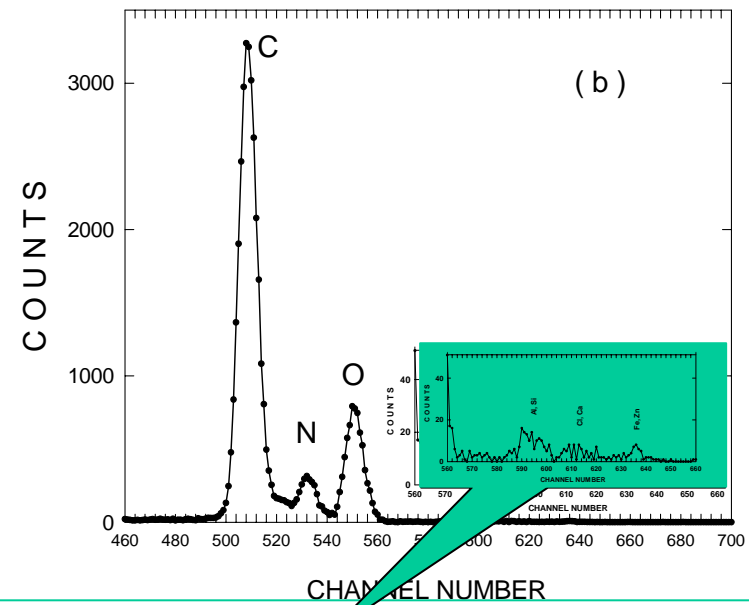
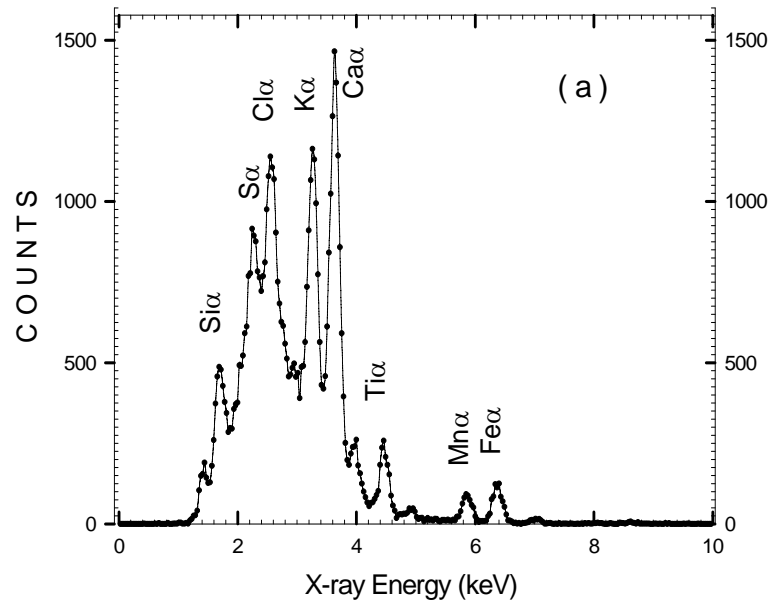
Target characterisation

Thickness: (mass/area i.e. g-mg- $\mu\text{g}/\text{cm}^2$)

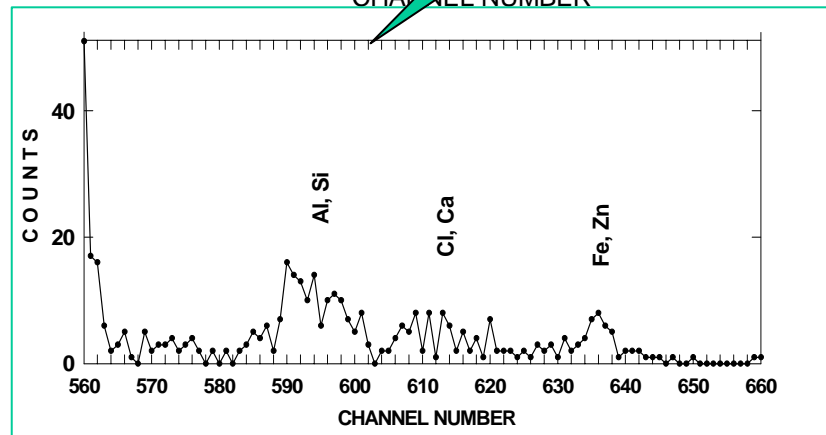
Thickness homogeneity (including surface topography)

Purity/composition

Purity/composition



PIXE spectrum of polyimide foil



~~Summary ?~~

Closing advices

- ↪ When ordering a target define the characteristic needed/significant for planned studies but avoid exaggeration i.e. do not order a target with much better characteristic than really needed. This may cause additional costs and/or ... delay.

element/isotope

thickness, dimensions

supported or not, if yes what can be considered as support

- ↪ Do not overestimate the importance of the chemical form of the target material

not always have to be a pure elemental form, the compounds may suite your

needs as well but often it is much easier (cheaper) to make the target from compound

- ↪ Never blindly believe the sample characteristic quoted. Whenever possible check yourself the characteristics which are of essential importance to your experiment.

- ↪ Discuss with target maker your planned target. Target preparation people can do sometimes more for you than you believe; it is often a question of communication and of raising the relevant problems/aspects.

Some target bibliography index on www.intds.org

